MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

TO-277-3LD
CASE 340BQ
ISSUE 0

DATE 30 SEP 2016

TOP VIEW

LAND PATTERN RECOMMENDATION

NOTES: UNLESS OTHERWISE SPECIFIED
A. PACKAGE REFERENCE: JEDEC TO-277
B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
C. ALL DIMENSIONS ARE IN MILLIMETERS.
D. DOES NOT COMPLY TO JEDEC STANDARD VALUE.

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